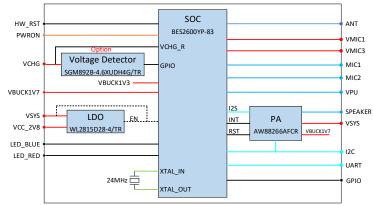


## Fully Integrated BT Audio SiP Solution for Smart Glasses

Goermicro GSBR-004A module is based on System in Package (SiP) technology which consists of a BES BES2600YP, Audio amplifier, LDO, Crystal and some other passive components. The SiP package technology combines several chipsets and many passive components. It significantly reduces the size of the product and provides more features in the same space for Truly Wireless Audio module.

## Features

- Dual-mode BT5.3 with LE audio
- Support ANC
- Flash: 8MB
- Pakage Size: 17.265 x 4 x 2.344mm<sup>3</sup>
- External interconnection mode: interposer VBUCK1V7
- Weight: 0.36g
- Supply Voltage Range : 3.1V ~ 5.5V
- Operating Temp. Range : -40~ +85°C



## Descriptions

| Item                                | Value | Unit | 1_       | n Pin1 Inde                      | x                       | 0.325<br>0.50                           |
|-------------------------------------|-------|------|----------|----------------------------------|-------------------------|---|
| Current Consumption                 |       |      |          |                                  | 0.75±0.042<br>0.60±0.03 | pin1 mark 0.25                          |
| Broadcast                           | 3     | mA   | 1        |                                  |                         |   |
| Shutdown                            | 4     | uA   | 1        |                                  | interposer 0.08+0.02 C  |   |
| Receiver                            |       |      | 1        |                                  | 5                       |   |
| BR Sensitivity                      | -94   | dBm  | ]        |                                  | (2.184)                 |   |
| BLE 1M Sensitivity                  | -98   | dBm  | ]        |                                  | Molding                 |   |
| BLE 2M Sensitivity                  | -94   | dBm  |          |                                  |                         |   |
| Transmitter                         |       |      | 265±0.10 | <b>├</b> ── <b>├</b> ── <b>├</b> |                         |   |
| BR Maximum RF<br>transmit power     | 16    | dBm  | 17.2     |                                  | Substrate               |   |
| BLE 1M Maximum<br>RF transmit power | 16    | dBm  |          |                                  |                         |   |
| BLE 2M Maximum<br>RF transmit power | 16    | dBm  |          |                                  | interposer              |   |
| Audio characteristics               |       |      |          |                                  |                         |   |
| SNR                                 | 74    | dB   | 1        |                                  | Solder Ball             |   |
| THD+N                               | -54   | dB   | ] -      | 4.000+0.10                       | B 0.334+0.03 0.75+0.042 | 0.325 0.25 interposer<br>0.50 pin1 mark |
|                                     | -     |      | -        | Top View                         | Side View               |   |
|                                     |       |      |          |                                  |                         | Goermicro                               |